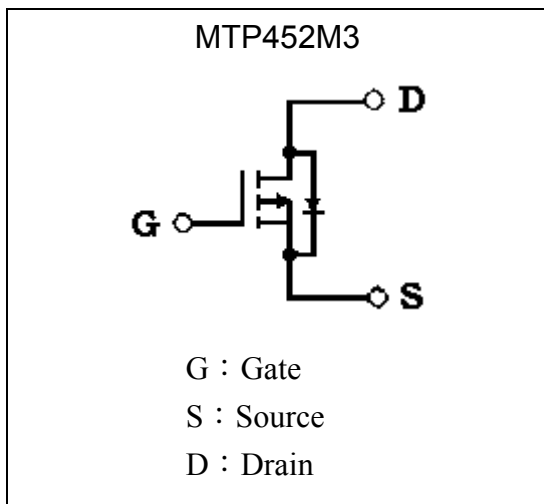
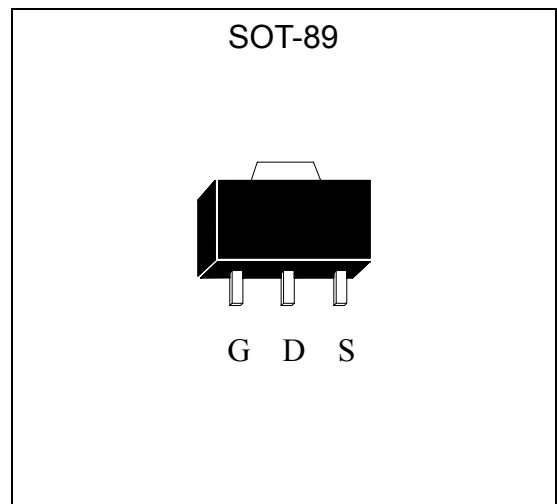


30V P-CHANNEL Enhancement Mode MOSFET

MTP452M3

Features

- Single Drive Requirement
- Low On-resistance, $R_{DS(ON)}=50m\Omega$ (typ.)@ $V_{GS}=-10V$, $I_D=-3.2A$
 $R_{DS(ON)}=72m\Omega$ (typ.)@ $V_{GS}=-4.5V$, $I_D=-2.6A$
- Ultra High Speed Switching
- Pb-free package

Symbol

Outline

Absolute Maximum Ratings ($T_A=25^\circ C$)

Parameter	Symbol	Limits	Unit
Drain-Source Voltage	V_{DS}	-30	V
Gate-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current @ $T_A=25^\circ C$	I_D	-5.3	A
Continuous Drain Current @ $T_A=70^\circ C$	I_D	-4.2	A
Pulsed Drain Current	I_{DM}	-20 *1, 3	A
Total Power Dissipation ($T_A=25^\circ C$)	P_D	2 *2	W
Total Power Dissipation ($T_A=70^\circ C$)		1.3 *2	
Operating Junction and Storage Temperature	T_j, T_{stg}	-55~+150	$^\circ C$

Note : *1. Pulse width limited by maximum junction temperature

 *2. Surface mounted on 1 in² copper pad of FR-4 board; 270 $^\circ C/W$ when mounted on min. copper pad

 *3. Pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$



Thermal Performance

Parameter	Symbol	Limit	Unit
Thermal Resistance, Junction-to-Ambient	Rth _{ja}	62.5	°C/W

Note : Surface mounted on 1 in² copper pad of FR-4 board.

Electrical Characteristics (T_j=25°C, unless otherwise noted)

Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Static					
BV _{DSS}	-30	-	-	V	V _{GS} =0, I _D =-250μA
V _{GS(th)}	-1.0	-1.6	-2.5	V	V _{DS} =V _{GS} , I _D =-250μA
G _{FS}	-	5.6	-	S	V _{DS} =-5V, I _D =-3A
I _{GSS}	-	-	±100	nA	V _{GS} =±20V, V _{DS} =0
I _{DSS}	-	-	-1	μA	V _{DS} =-30V, V _{GS} =0
	-	-	-25	μA	V _{DS} =-24V, V _{GS} =0 (T _j =70°C)
*R _{DS(ON)}	-	50	60	mΩ	I _D =-3.2A, V _{GS} =-10V
	-	72	80		I _D =-2.6A, V _{GS} =-4.5V
Dynamic					
C _{iss}	-	619	-	pF	V _{DS} =-25V, V _{GS} =0, f=1MHz
C _{oss}	-	55	-		
C _{rss}	-	49	-		
*t _{d(ON)}	-	7	-	ns	V _{DS} =-15V, I _D =-1A, V _{GS} =-10V R _G =3.3Ω
*t _r	-	3	-		
*t _{d(OFF)}	-	20	-		
*t _f	-	15	-		
*Q _g	-	11	-	nC	V _{DS} =-15V, I _D =-5.3A, V _{GS} =-10V,
*Q _{gs}	-	2.3	-		
*Q _{gd}	-	4.3	-		
Source-Drain Diode					
*V _{SD}	-	-0.8	-1.2	V	V _{GS} =0V, I _S =-1.2A
*t _{rr}	-	22	-	ns	I _S =-3.2A, V _{GS} =0, dI/dt=100A/μs
*Q _{rr}	-	18	-	nC	

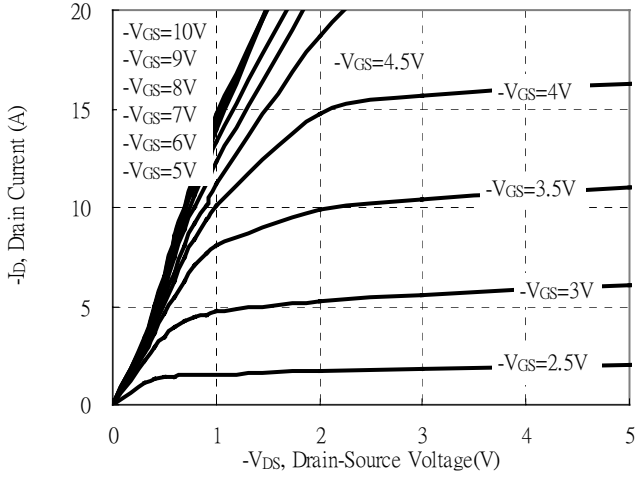
*Pulse Test : Pulse Width ≤300μs, Duty Cycle≤2%

Ordering Information

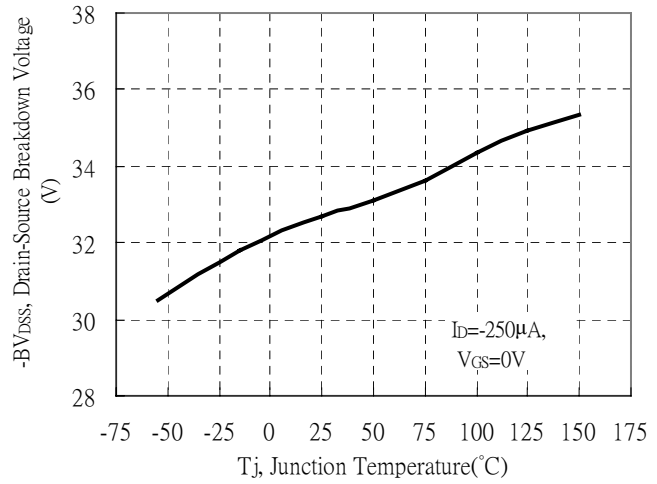
Device	Package	Shipping	Marking
MTP452M3	SOT-89 (Pb-free)	1000 pcs / Tape & Reel	452

Typical Characteristics

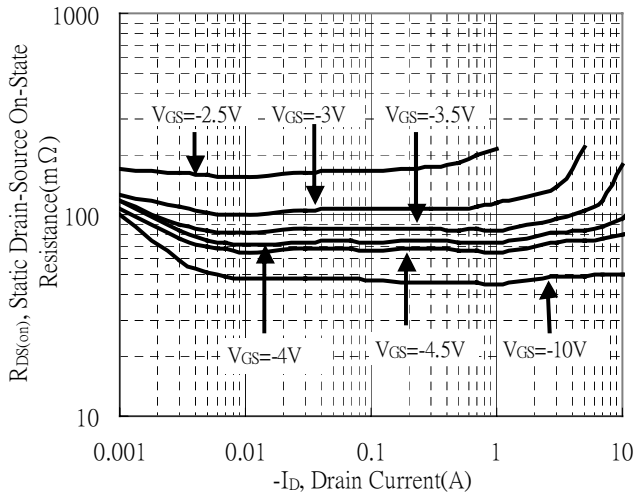
Typical Output Characteristics



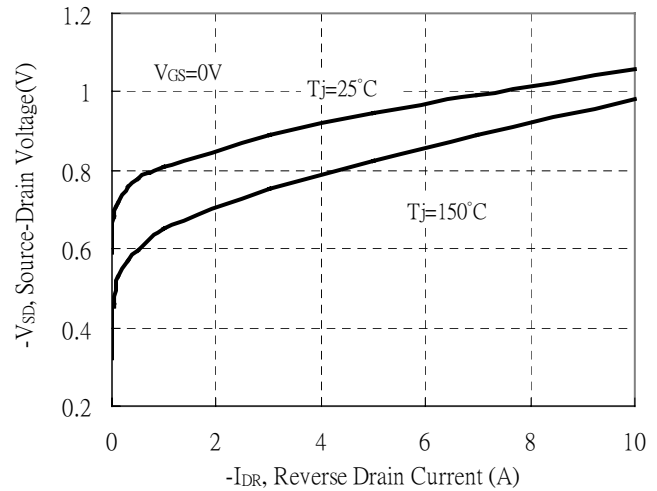
Brekdown Voltage vs Ambient Temperature



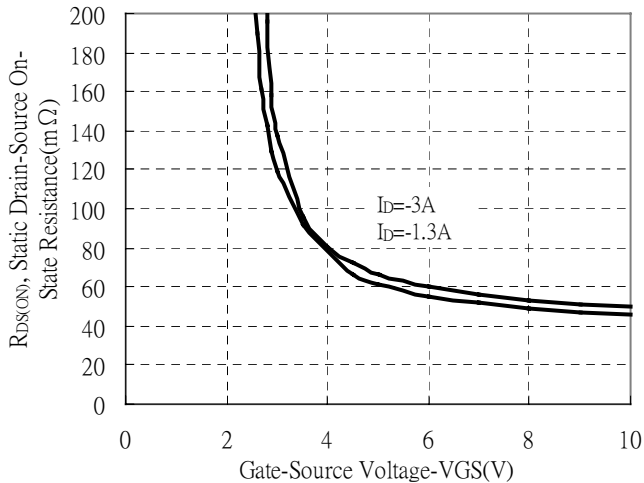
Static Drain-Source On-State resistance vs Drain Current



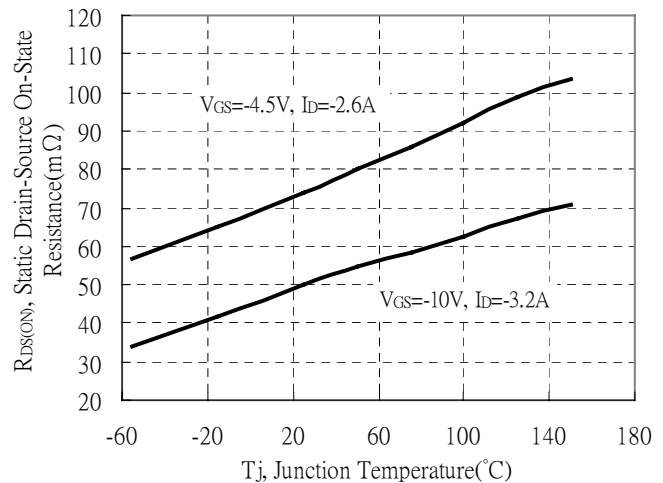
Reverse Drain Current vs Source-Drain Voltage



Static Drain-Source On-State Resistance vs Gate-Source Voltage

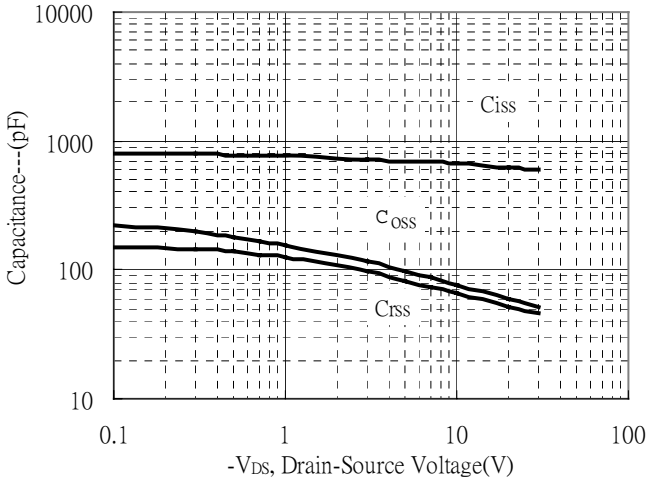


Drain-Source On-State Resistance vs Junction Temperature

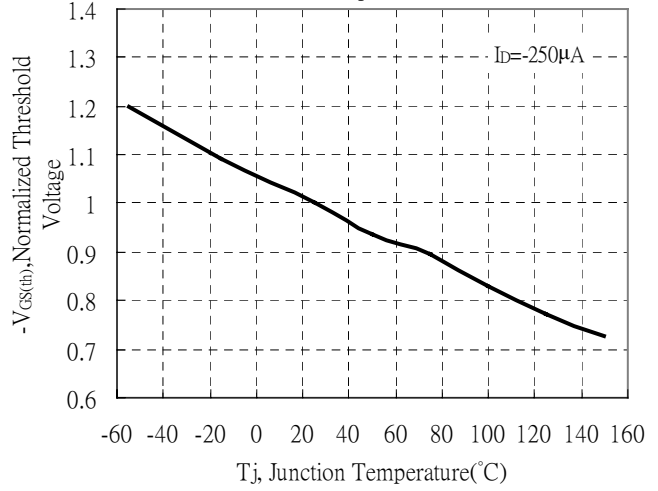


Typical Characteristics(Cont.)

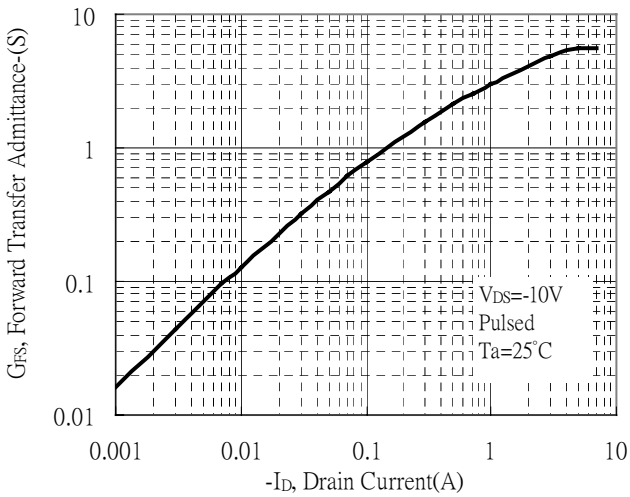
Capacitance vs Drain-to-Source Voltage



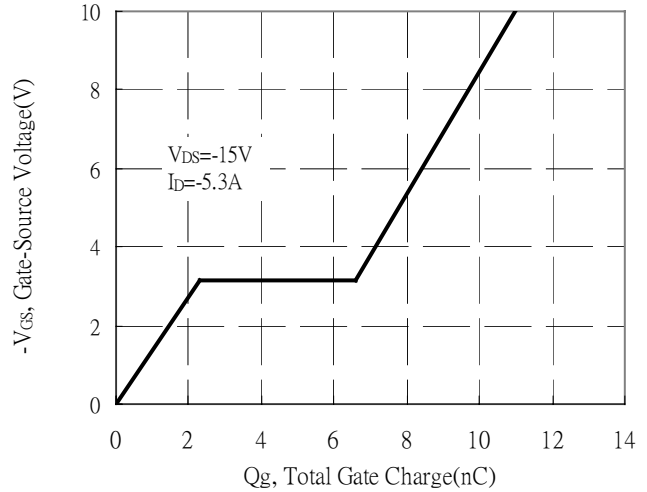
Normalized Threshold Voltage vs Junction Temperature



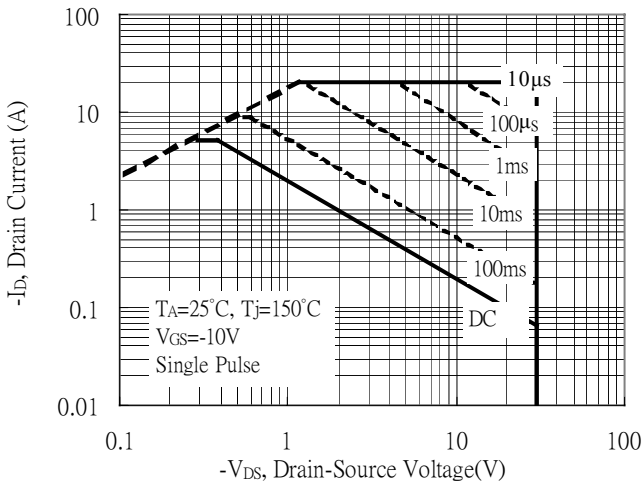
Forward Transfer Admittance vs Drain Current



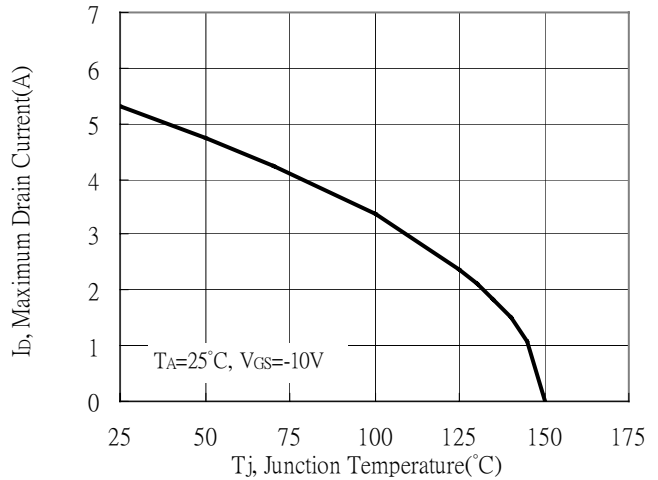
Gate Charge Characteristics



Maximum Safe Operating Area

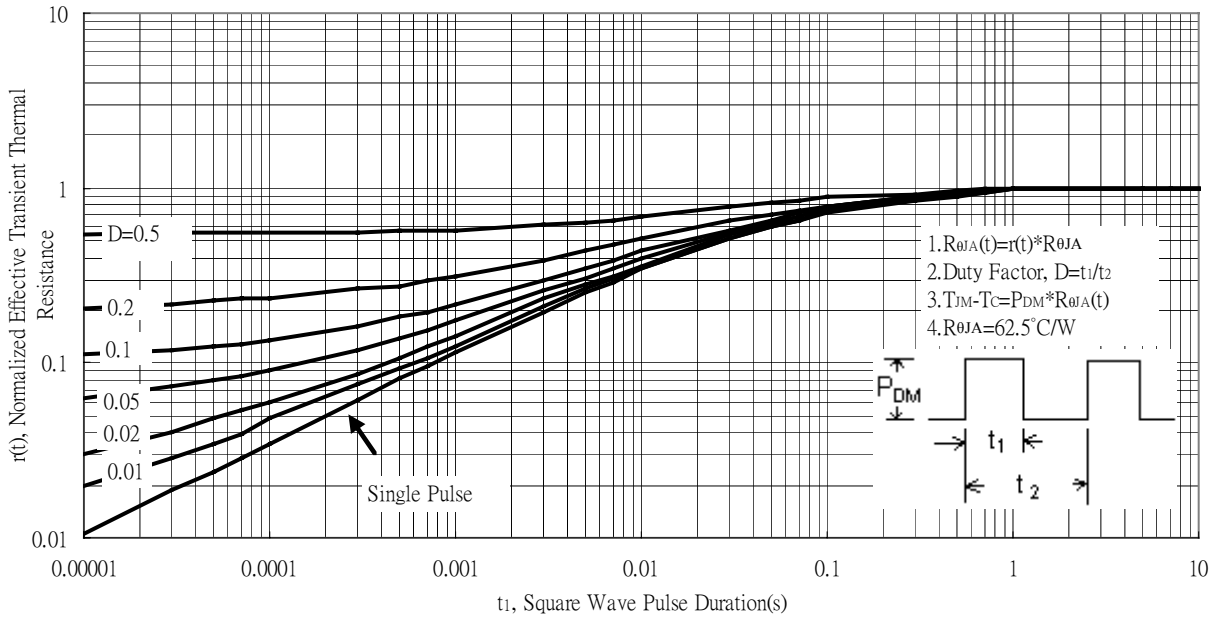


Maximum Drain Current vs Junction Temperature

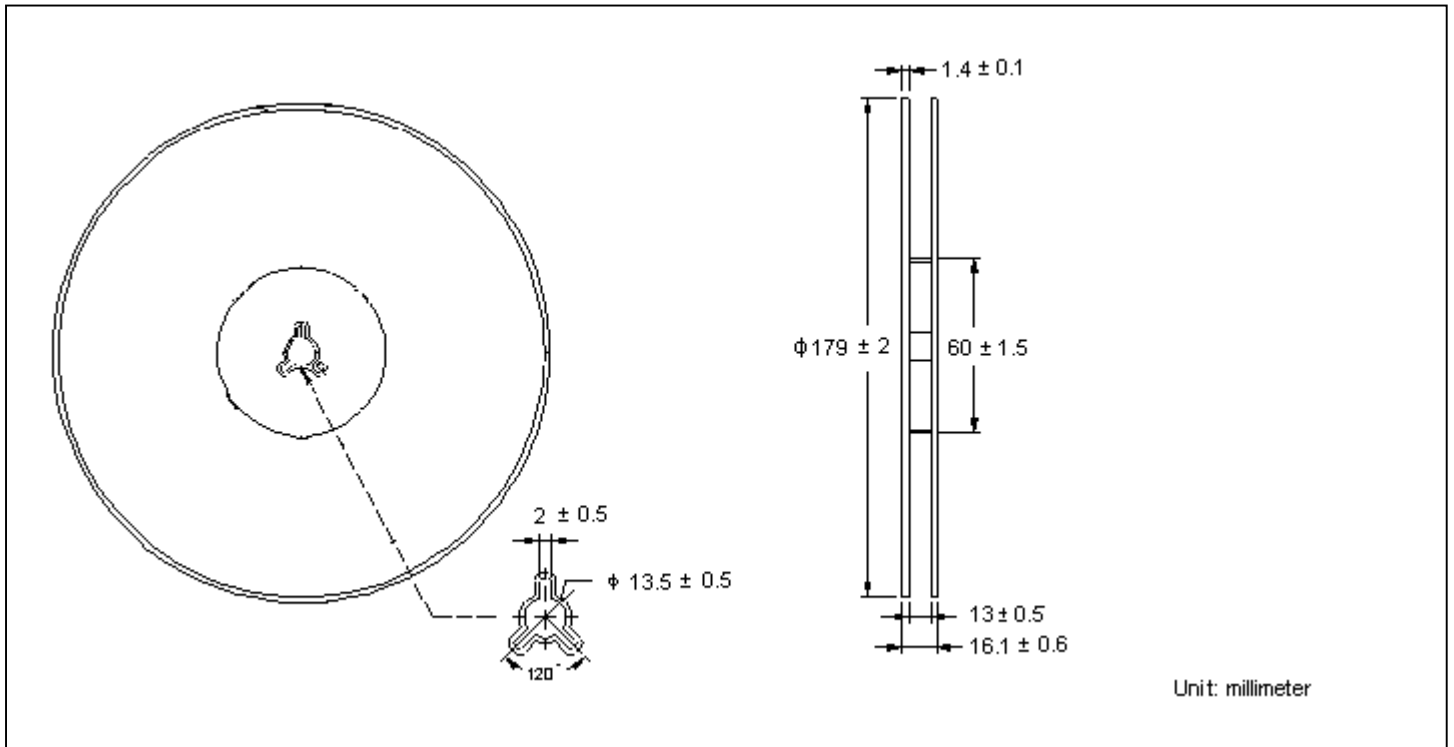


Typical Characteristics(Cont.)

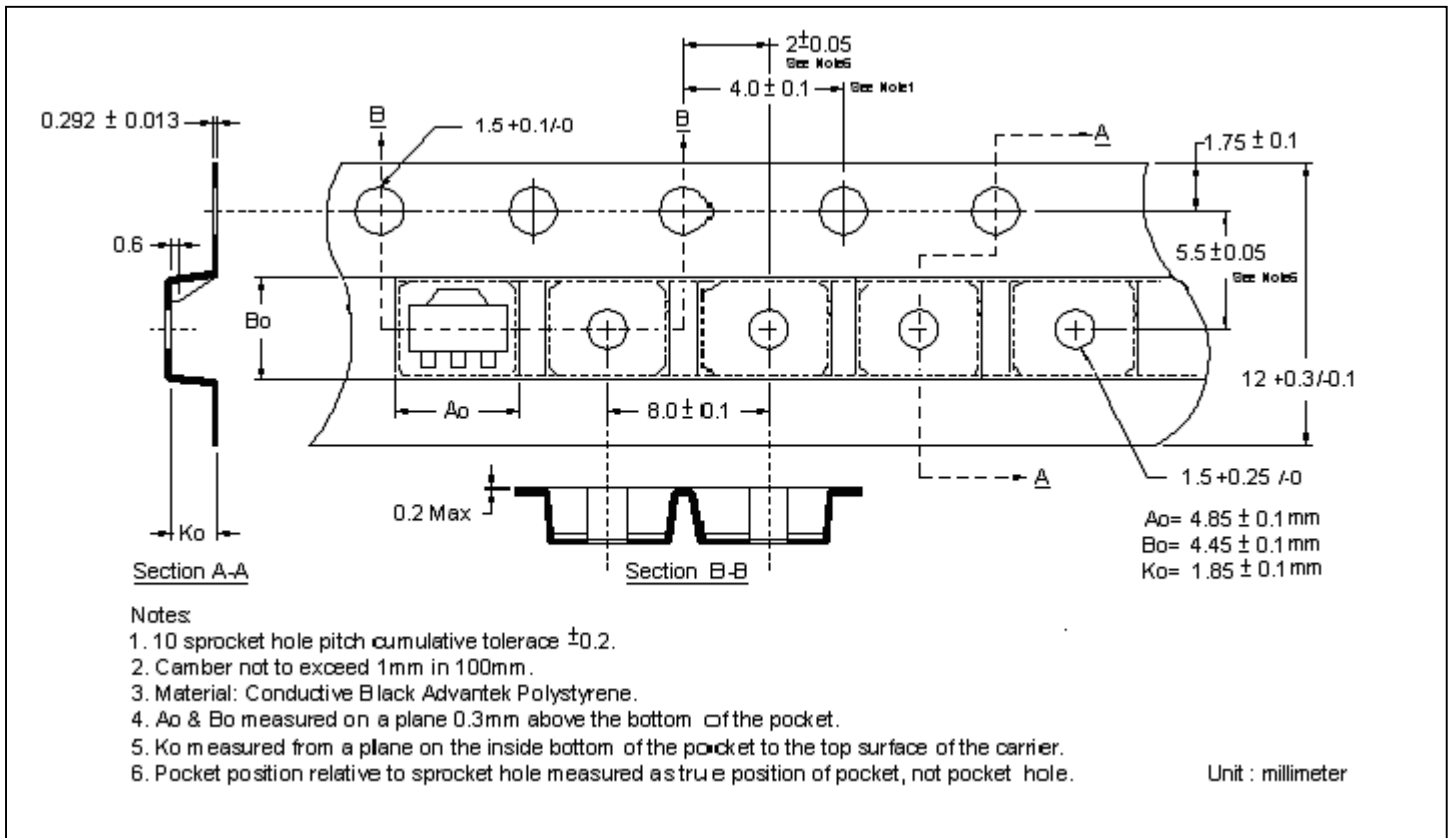
Transient Thermal Response Curves



Reel Dimension



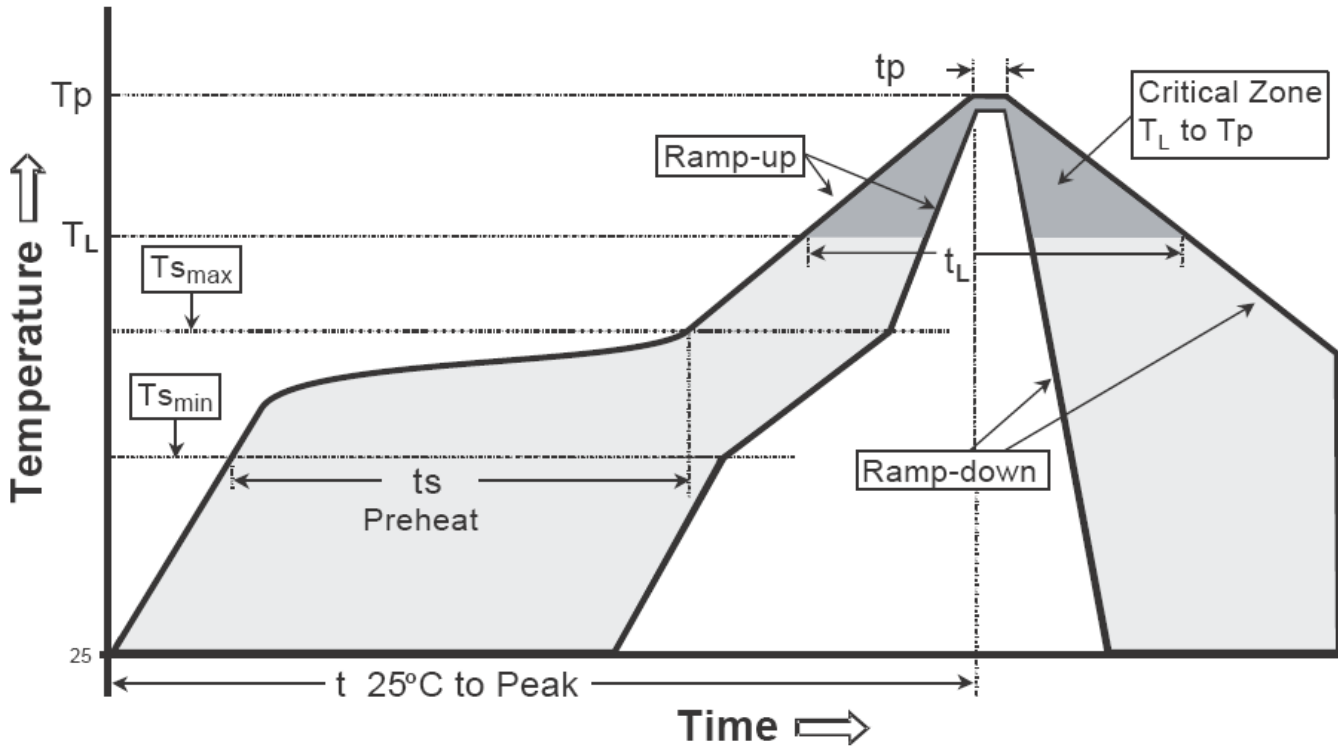
Carrier Tape Dimension



Recommended wave soldering condition

Product	Peak Temperature	Soldering Time
Pb-free devices	260 +0/-5 °C	5 +1/-1 seconds

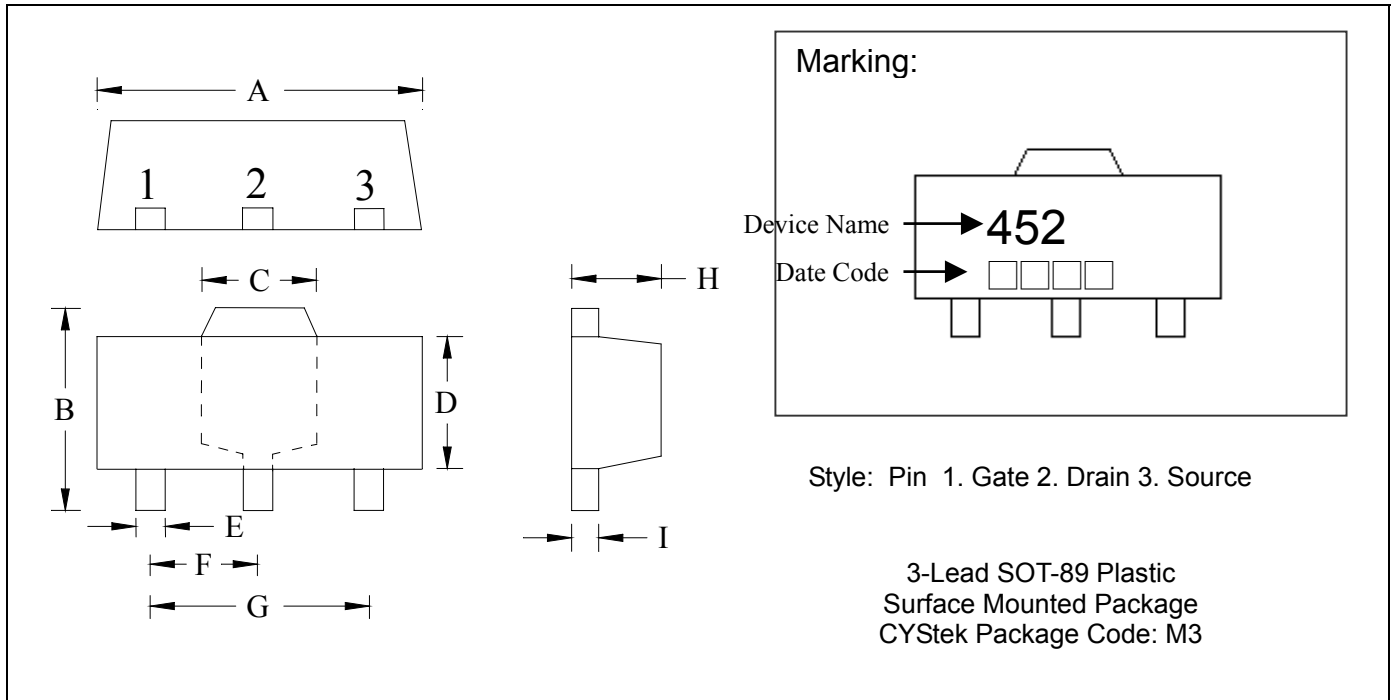
Recommended temperature profile for IR reflow



Profile feature	Sn-Pb eutectic Assembly	Pb-free Assembly
Average ramp-up rate (T _{smax} to T _p)	3°C/second max.	3°C/second max.
Preheat -Temperature Min(T _{s min}) -Temperature Max(T _{s max}) -Time(t _{s min} to t _{s max})	100°C 150°C 60-120 seconds	150°C 200°C 60-180 seconds
Time maintained above: -Temperature (T _L) - Time (t _L)	183°C 60-150 seconds	217°C 60-150 seconds
Peak Temperature(T _P)	240 +0/-5 °C	260 +0/-5 °C
Time within 5°C of actual peak temperature(tp)	10-30 seconds	20-40 seconds
Ramp down rate	6°C/second max.	6°C/second max.
Time 25 °C to peak temperature	6 minutes max.	8 minutes max.

Note : All temperatures refer to topside of the package, measured on the package body surface.

SOT-89 Dimension



*: Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.1732	0.1811	4.40	4.60	F	0.0583	0.0598	1.48	1.527
B	0.1594	0.1673	4.05	4.25	G	0.1165	0.1197	2.96	3.04
C	0.0591	0.0663	1.50	1.70	H	0.0551	0.0630	1.40	1.60
D	0.0945	0.1024	2.40	2.60	I	0.0138	0.0161	0.35	0.41
E	0.01417	0.0201	0.36	0.51					

Notes: 1.Controlling dimension: millimeters.

2.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.

3.If there is any question with packing specification or packing method, please contact your local CYStek sales office.

Material:

- Lead: Pure tin plated.
- Mold Compound: Epoxy resin family, flammability solid burning class: UL94V-0.

Important Notice:

- All rights are reserved. Reproduction in whole or in part is prohibited without the prior written approval of CYStek.
- CYStek reserves the right to make changes to its products without notice.
- CYStek **semiconductor products are not warranted to be suitable for use in Life-Support Applications, or systems.**
- CYStek assumes no liability for any consequence of customer product design, infringement of patents, or application assistance.